

September 2010

DB3-DB3TG 150mW Bi-directional Trigger Diodes

Features

- V_{BO}: 32V Version
- · Low break-over current
- DO-35 package (JEDEC)
- · Hermetically sealed glass
- · Compression bonded construction
- All external surfaces are corrosion resistant and terminals are readily solderable
- · RoHS compliant
- High reliability glass passivation insuring parameter stability and protection against junction contamination.
- Terminal: Pure tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed
- High temperature soldering guaranteed : 260°C/10 seconds



DO-35

Absolute Maximum Ratings and Electrical Characteristics

Symbol	Parameter		Value		Units
Symbol	r arameter	DB3	DB3TG	Ullits	
V_{BO}	Break-over Voltage @ C=22nF	Min.	28	30	V
		Тур.	32	32	V
		Max.	36	34	V
±V _{BO}	Break-over Voltage Symmetry @ C=22nF	Max.	±3	±2	V
I _{BO}	Break-over Current @ C=22nF	Max.	100	15	μА
Δ٧	Dynamic Break-over Voltage @ I_{BO} to I_F =10mA	Min.	5	9	V
I _B	Leakage Current @ V _B =0.5V _{BO} (Max.) Max.		10		μΑ
V _O	Output Voltage *see diagram 1	Min.	!	5	V
P_{D}	Power Dissipation	150		mW	
I _{FRM}	Repetitive Peak Forward Current, Pulse Width=20	2		Α	
$R_{\theta ja}$	Typical Thermal Resistance, Junction to Ambient (400		°C/W	
T _{J,} T _{STG}	Junction and Storage Temperature Range	-40 to +125		°C	

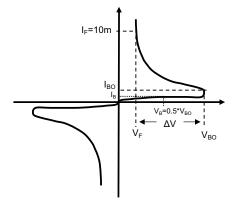
^{*} Rating at 25°C ambient temperature unless otherwise specified.

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^{*} Notes: 1. Valid provided that electrodes are kept at ambient temperature

Typical Performance Characteristics



 $\begin{array}{lll} \textbf{V}_{\text{Bo}} & : \text{Break-Over Voltage} \\ \textbf{I}_{\text{BO}} & : \text{Break-Over Current} \\ \textbf{\Delta V} & : \text{Dynamic Breakover Voltage} \\ \textbf{I}_{\text{B}} & : \text{Leakage Current at V}_{\text{B}}{=}0.5^{*}\text{V}_{\text{BO}} \end{array}$

: Voltage at Current I_F=10mA

Diagram 1 : Test circuit

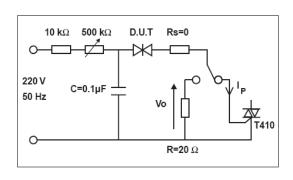


Figure 1. Admissible Power Dissipation Curve

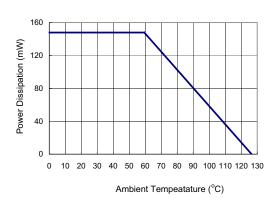


Figure 2. Relative Variation of VBO versus Junction Temperature

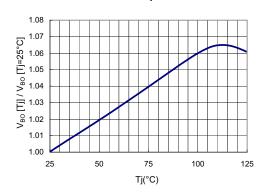
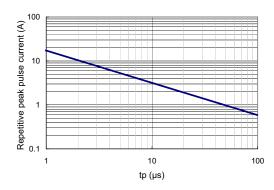


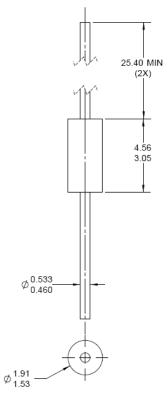
Figure 3. Repetitive Peak Pulse Current versus Pulse Duration (maximum values)



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Physical Dimensions

DO-35



NOTES: UNLESS OTHERWISE SPECIFIED

- PACKAGE STANDARD REFERENCE:
 JEDEC DO-204, VARIATION AH.
 HERMETICALLY SEALED GLASS PACKAGE.
 PACKAGE WEIGHT IS 0.137 GRAM.
 D ALL DIMENSIONS ARE IN MILLIMETERS.
 DRAWING FILE NAME: DO35AREV02

Dimensions in Millimeters



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Definition of Terms						
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